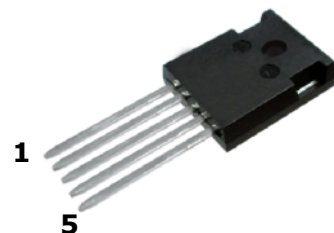
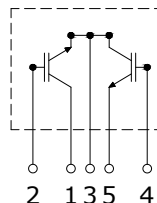


PRELIMINARY DATASHEET
Fast IGBT in NPT Technology
Series 2x1200, 8A in TO247 Package

- Short circuit withstand time – 10 μ s
- Designed for motor controls, inverters and SMPS
- High ruggedness, temperature stability
 - parallel switching capability
- Pb-free lead finish; RoHS compliant


MAXIMUM RATINGS (per IGBT), at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Units
Collector-emitter voltage	V_{CE}	1200	V
DC collector current, limited by T_{jmax} $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_C	16.5 7.9	A
Pulsed collector current, t_D limited by T_{jmax}	I_{Cpulse}	27	
Turn off safe operating area $V_{CE} \leq 1200\text{V}$, $T_j \leq 150^\circ\text{C}$	-	27	
Gate-emitter voltage	V_{GE}	± 20	V
Avalanche energy, single pulse $I_C = 8\text{A}$, $V_{CC} = 50\text{V}$, $R_{GE} = 25\Omega$, start at $T_j = 25^\circ\text{C}$	E_{AS}	40	mJ
Short circuit withstand time ¹ $V_{GE} = 15\text{V}$, $100 < V_{CC} \leq 1200\text{V}$, $T_j \leq 150^\circ\text{C}$	t_{SC}	10	μs
Soldering temperature Wave soldering, 1.6 mm (0.063 in.) from case for 10s	T_S	260	$^\circ\text{C}$
Operating junction and storage temperature	T_j, T_{stg}	-55... +150	$^\circ\text{C}$

Thermal Resistance (per IGBT)

Parameter	Symbol	Max. Value	Units
Characteristics			
IGBT thermal resistance, junction to case	R_{thJC}	1.25	K/W
Thermal resistance, junction to ambient	R_{thJA}	62	

¹ Allowed number of short circuits: < 1000; time between short circuits: > 1s.

CAUTION: These devices are ESD sensitive. Use proper handling procedure.

ELECTRICAL CHARACTERISTICS (per IGBT), at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Characteristics						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0\text{V}, I_C = 500\mu\text{A}$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15\text{V}, I_C = 8\text{A}$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	2.5 -	3.1 3.7	3.6 4.3	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 350\mu\text{A}, V_{CE} = V_{GE}$	3.0	4.0	5.0	
Zero gate voltage collector current	I_{CES}	$V_{CE} = 1200\text{V}, V_{GE} = 0$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	- -	- -	100 400	μA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0\text{V}, V_{GE} = 20\text{V}$	-	-	100	nA
Transconductance	g_{fs}	$V_{CE} = 20\text{V}, I_C = 8\text{A}$	-	6	-	S
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{CE} = 25\text{V},$ $V_{GE} = 0\text{V},$ $f = 1\text{MHz}$	-	720	-	pF
Output capacitance	C_{oss}		-	60	-	
Reverse transfer capacitance	C_{rss}		-	40	-	
Gate charge	Q_{Gate}	$V_{CC} = 960\text{V}, I_C = 8\text{A}$ $V_{GE} = 15\text{V}$	-	70	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E		-	7	-	nH
Short circuit collector current ¹	$I_{C(SC)}$	$V_{GE} = 15\text{V}, t_{SC} \leq 10\mu\text{s}$ $100\text{V} \leq V_{CC} \leq 1200\text{V},$ $T_j = 150^\circ\text{C}$	-	75	-	A

SWITCHING CHARACTERISTICS (per IGBT), Inductive Load at $T_j = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
IGBT Characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{CC}=800\text{V}, I_C=8\text{A},$ $V_{GE}=0/15\text{V},$ $R_G=47\Omega,$ $L_\sigma^2 = 180\text{nH},$ $C_\sigma^2 = 40\text{pF}$ Energy losses include tail and diode reverse recovery.	-	27	-	ns
Rise time	t_r		-	29	-	
Turn-off delay time	$t_{d(off)}$		-	440	-	
Fall time	t_f		-	21	-	
Turn-on energy	E_{on}		-	0.6	-	mJ
Turn-off energy	E_{off}		-	0.4	-	
Total switching energy	E_{ts}		-	1.0	-	

SWITCHING CHARACTERISTICS (per IGBT), Inductive Load at $T_j = 150^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
IGBT Characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{CC}=800\text{V}, I_C=8\text{A},$ $V_{GE}=0/15\text{V},$ $R_G=47\Omega,$ $L_\sigma^2 = 180\text{nH},$ $C_\sigma^2 = 40\text{pF}$	-	30	-	ns
Rise time	t_r		-	26	-	
Turn-off delay time	$t_{d(off)}$		-	490	-	
Fall time	t_f		-	30	-	

Turn-on energy	E_{on}	Energy losses include tail and diode reverse recovery.	-	1.0	-	mJ
Turn-off energy	E_{off}		-	0.7	-	
Total switching energy	E_{ts}		-	1.7	-	

1 Allowed number of short circuits: < 1000; time between short circuits: > 1s.
 2 Leakage inductance L_s and Stray capacity C_s due to dynamic test circuit.

Package Outline Drawing

